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Date:

July 1, 2005

To:

Examiner F. Toledo

U.S. Patent Office

Fax No:

703-872-9306

Ph. No:

From:

Andrew J. Telesz, Jr.

Subject: Serial No.: 10/689,936

Our Ref. No.: 11Z.003D2C

No. of Pages (including cover):

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CERTIFICATE OF TALASHI OH		Docket No. IIZ.003D2C					
Serial No. 10/689,936	Filing Date October 22, 2003	Examiner F. Toledo		Group Art Unit 2823			
Invention: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS							
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AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Takashi Ohsumi				Docket No. IIZ.003D2C			
Application No. 10/689,936	Filing Date October 22, 2003	Examiner F. Toledo	•		10.	Group Art Un 2823	t Confirmation No. 4027
Invention: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED							
COMMISSIONER FOR PATENTS:  Transmitted herewith is an amendment in the above-identified application.  The fee has been calculated and is transmitted as shown below.							
		CLAIMS AS AM	ENDED	)			
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR		ER EXTRA		RATE	ADDITIONAL FEE
TOTAL CLAIMS	2 -	20 =		0	×	\$50.00	\$0.00
INDEP. CLAIMS	1 -	3 .=		0	×	\$200.00	\$0.00
Multiple Dependen	t Claims (check if appl	licable) 🔘		_			\$0.00
		TOTAL ADDITIONAL F	EE FO	R THIS AME	ENC	MENT	\$0.00
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11951 FREEDOM DRIVE, SUITE 1260 RESTON, VA 20190 TEL. NO. (571) 283-0720  Signature of Person Mailing Correspondence  CC:  Typed or Printed Name of Person Mailing Correspondence							

AMENDMENT TRANSMITTAL LETTER (Large Entity) Applicant(s): Takashi Ohsumi					Docket No. IIZ.003D2C		
Application No. 10/689,936	Filing Date October 22, 2003	Examiner F. Toledo		Customer N 20987	٠٥٠	Group Art Unit 2823	Confirmation No. 4027
Invention: METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS INCLUDING A SEALING MEMBER WITH REDUCED							
COMMISSIONER FOR PATENTS:  Transmitted herewith is an amendment in the above-identified application.  The fee has been calculated and is transmitted as shown below.							
		CLAIMS AS AM	ENDEC	) .			
	CLAIMS REMAINING AFTER AMENOMENT	HIĞHEST # PREV. PAID FÖR		ER EXTRA		RATE	ADDITIONAL FEE
TOTAL CLAIMS	2 -	20 =		0	×	\$50.00	\$0.00
INDEP. CLAIMS	1 -	3 =		0	x	\$200.00	\$0.00
Multiple Dependent	Multiple Dependent Claims (check if applicable)						
		TOTAL ADDITIONAL F	EE FO	R THIS AME	ENÇ	MENT	\$0.00
No additional fee is required for amendment.  Please charge Deposit Account No. In the amount of A check in the amount of to cover the filing fee is enclosed.  The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account 50-0238 Any additional filing fees required under 37 C.F.R. 1.16. Any patent application processing fees under 37 CFR 1.17.  Payment by credit card. Form PTO-2038.  WARNING: Information on this form may become public. Credit card Information should not be included on this form. Provide credit card. Information and authorization on PTO-2038.  ANDREW J. TELESZ, JR.  REG. NO. 33,581  Dated: July 1, 2005  I hereby certify that this correspondence is being, deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents."  P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR 1.8(a)] on (Date)  (Date)							
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Via Facsimile (703) 872-9306

Serial No. 10/689,936

I/Z.003D2C

Amendment Under 37 C.F.R. 1.312 dated July 1, 2005

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Takashi Ohsumi Group Art Unit: 2823

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Serial No.: 10/689,936

Examiner: F. Toledo

JUL 0 1 2005

Filed: October 22, 2003

Confirm. No.: 4027

For:

METHOD FOR FABRICATING A SEMICONDUCTOR APPARATUS

INCLUDING A SEALING MEMBER WITH REDUCED THERMAL STRESS

## AMENDMENT UNDER 37 C.F.R. 1.312

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Date: July 1, 2005

Sir:

Responsive to the Notice of Allowance dated June 15, 2005, the following amendments and remarks are respectfully submitted in connection with the aboveidentified application under 37 C.F.R. 1.312.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.

Page 1 of 4